



Integrated Device Technology, Inc.  
2975 Stender Way, Santa Clara, CA - 95054

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: <b>SR-0403-02</b>	DATE: 3/5/2004	MEANS OF DISTINGUISHING CHANGED DEVICES: <input type="checkbox"/> Product Mark <input checked="" type="checkbox"/> Back Mark      Lot number will have "K" prefix. <input type="checkbox"/> Date Code <input type="checkbox"/> Other
Product Affected: PB36 (400 mil SOJ) package type (see attachment for affected part #s)		
Date Effective: 6/5/2004		

Contact: Geoffrey Cortes	Attachment:: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
Title: Corporate QA / Reliability Manager	
Phone #: (408) 492- 8321	
Fax #: (408) 727-2328	Samples: See attachment
E-mail: <a href="mailto:Geoffrey.Cortes@idt.com">Geoffrey.Cortes@idt.com</a>	

**DESCRIPTION AND PURPOSE OF CHANGE:**

- Die Technology
- Wafer Fabrication Process
- Assembly Process
- Equipment
- Material
- Testing
- Manufacturing Site      To transfer the assembly of PB36 (400 mil SOJ) from Amkor Technology Korea (ATK) to IDT-Manila (Philippines) facility. The other (400 mil SOJ) packages are qualified and are presently being assembled at IDT-Philippines.
- Data Sheet
- Other

**RELIABILITY/QUALIFICATION SUMMARY:**  
Please see attachment for reliability/qualification data.

**CUSTOMER ACKNOWLEDGMENT OF RECEIPT:**  
IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.  
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	<input type="checkbox"/> <b><i>Approval for shipments prior to effective date.</i></b>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____
<b>CUSTOMER COMMENTS:</b> _____	

**IDT ACKNOWLEDGMENT OF RECEIPT:**  
RECD. BY: \_\_\_\_\_ DATE: \_\_\_\_\_



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### ATTACHMENT - PCN #: SR-0403-02

**PCN Type:** Assembly Facility Change

**Data Sheet Change:** There is no change in Moisture Sensitive Level (MSL).

**Detail of Change:** IDT-Manila (Philippines) is a qualified assembly facility for (SOJ) package family. IDT is transferring an additional package type to this facility.

There is no change in the assembly material set and the package tooling will be transferred from Amkor Technology Korea (ATK) to IDT-Manila (Philippines) facility.

Description	Assembly Facility Change	
	From	To
PB36 (SOJ) packages	Amkor Technology Korea (ATK)	IDT-Manila (Philippines)

The affected products are as follow:

IDT71V424L10Y	IDT71V424L15YI	IDT71V424S12YI
IDT71V424L12Y	IDT71V424S10Y	IDT71V424S15Y
IDT71V424L12YI	IDT71V424S10YI	IDT71V424S15YI
IDT71V424L15Y	IDT71V424S12Y	

Note: For T & R (shipping method) "8" is added to the part number and for industrial grade, letter "I" is added to the part number.

**Samples are not built ahead of the change and are limited to selective devices. Please contact your local field sales representative for sample availability and additional information.**



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## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### ATTACHMENT - PCN #: SR-0403-02

**Qualification Plan:** P03-10-03  
**Test Vehicle:** IDT71V424  
**Qualification Test Plan and Results:**

Test Description	Test Method	Sample Size /# of Fails	Test Results
*Highly Accelerated Stress Test (HAST) (100 Hrs, @ 130°C/85%RH,Static Bias)	JESD22-A110-B	45/0	45/0
*Temperature Cycling (-65°C to +150°C, 500 cycle)	JESD22-A104-B	45/0	45/0
*Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	JESD22-A102-C	45/0	45/0
Physical Dimensions	JESD22-B100-B	5/0	5/0
Resistance to Solvents	MIL-STD-883, M 2015	3/0	3/0
Solderability	JESD22-B102-C J-STD-002	3/0	3/0
Bake & Ball Shear Test	JESD22-B116	5/0	5/0
Bond Pull Test	MIL-STD-883, M 2011	5/0	5/0
X-ray Examination	MIL-STD-883, M 2015	45/0	45/0
Adhesion of Lead Finish	MIL-STD-883, M 2025	3/0	3/0
Lead Integrity Test	JESD22-B105C	3/0	3/0
External Visual Inspection	JESD22-B101	25/0	25/0
Internal Visual Inspection	MIL-STD-883, M 2010	5/0	5/0
Moisture Sensitive Level	J-STD-020B	90/0	90/0

Notes: \* Test requires moisture pre-conditioning sequence per JESD22-A113C.